

NZL5V6AXV3T1 Series

Preferred Devices

Dual Common Anode ESD Protection Diodes

SC-89 Package

These dual monolithic silicon ESD protection diodes are intended for use in voltage- and ESD-sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. Their dual junction common anode design protects two separate lines using only one package. These devices are ideal for situations where board space is at a premium.

Specification Features:

- SC-89 Package Allows Either Two Separate Unidirectional Configurations or a Single Bidirectional Configuration
- ESD Rating of Class N (exceeding 16 kV) per the Human Body Model
- Meets IEC61000-4-2 Level 4
- Low Leakage < 5.0 μ A
- These are Pb-Free Devices

Mechanical Characteristics:

CASE: Void-free, Transfer-molded, Thermosetting Plastic
Epoxy Meets UL 94, V-0

LEAD FINISH: 100% Matte Sn (Tin)

MOUNTING POSITION: Any

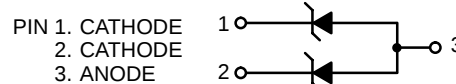
QUALIFIED MAX REFLOW TEMPERATURE:

260°C Device Meets MSL 1 Requirements



ON Semiconductor®

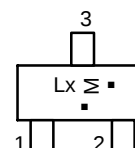
<http://onsemi.com>



MARKING DIAGRAM



**SC-89
CASE 463C
STYLE 4**



L = Device Code
x = Specific Device
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NZL5V6AXV3T1	SC-89*	3000/Tape & Reel
NZL5V6AXV3T1G	SC-89*	3000/Tape & Reel
NZL6V8AXV3T1	SC-89*	3000/Tape & Reel
NZL6V8AXV3T1G	SC-89*	3000/Tape & Reel
NZL6V8AXV3T3G	SC-89*	10000/Tape & Reel
NZL7V5AXV3T1	SC-89*	3000/Tape & Reel
NZL7V5AXV3T1G	SC-89*	3000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

*This package is inherently Pb-Free.

DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the table on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Total Power Dissipation on FR-5 Board (Note 1) @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	240 1.9	mW mW/ $^\circ\text{C}$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	525	$^\circ\text{C/W}$
Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$
Lead Solder Temperature – Maximum (10 Second Duration)	T_L	260	$^\circ\text{C}$
IEC61000-4-2 (Contact)		10	kV

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 board with minimum recommended mounting pad.

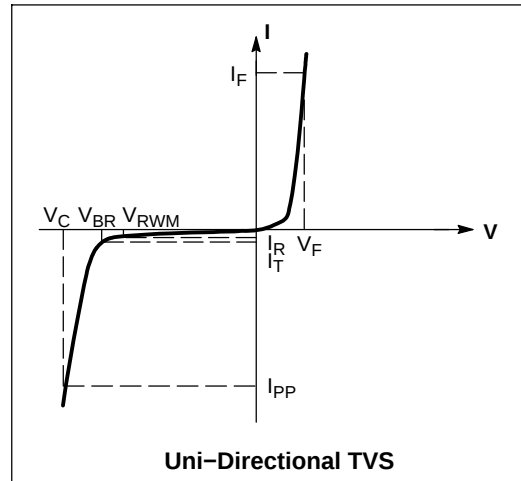
*Other voltages may be available upon request.

ELECTRICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise noted)

UNIDIRECTIONAL (Circuit tied to Pins 1 and 3 or 2 and 3)

Symbol	Parameter
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F



ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted, $V_F = 0.9\text{ V Max}$ @ $I_F = 10\text{ mA}$ for all types)

UNIDIRECTIONAL (Circuit tied to Pins 1 and 3 or Pins 2 and 3)

Device	Device Marking	V_{RWM} V	I_R @ V_{RWM} μA	Breakdown Voltage				Surge			
				V_{BR} (Note 2) (V)			@ I_{ZT} mA	V_C (V) @ $I_{PP} = 1.0\text{ A}^\dagger$	V_C (V) @ $\text{Max } I_{PP}^\dagger$	$\text{Max } I_{PP}$ (A) †	P_{pk} (W) †
				Min	Nom	Max		Typ	Max		Typ
NZL5V6AXV3T1	L0	3.0	5.0	5.32	5.6	5.88	5.0	7.0	10.1	4.8	50
NZL6V8AXV3T1	L2	4.5	1.0	6.46	6.8	7.14	5.0	7.9	11.9	6.7	73
NZL6V8AXV3T3	L2	4.5	1.0	6.46	6.8	7.14	5.0	7.9	11.9	6.7	73
NZL7V5AXV3T1	L3	5.0	1.0	7.12	7.5	7.88	5.0	8.8	13.5	5.7	75

2. V_{BR} measured at pulse test current I_T at an ambient temperature of 25°C .

† Surge current waveform per Figure 5.

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TYPICAL CHARACTERISTICS

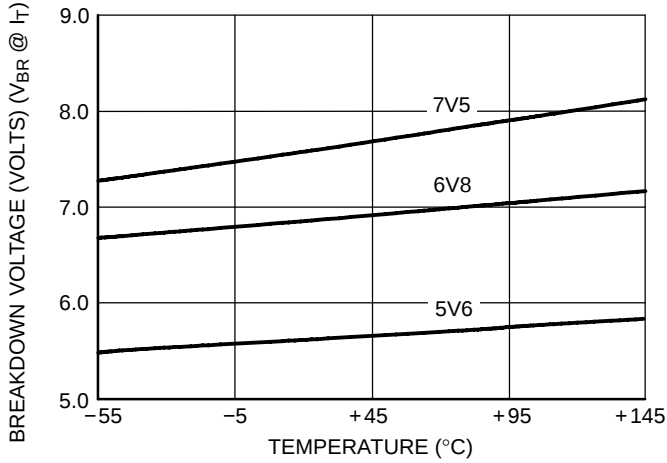


Figure 1. Typical Breakdown Voltage versus Temperature

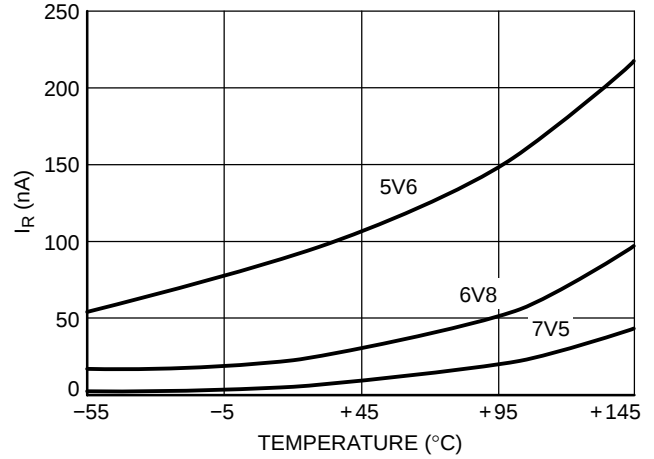


Figure 2. Typical Leakage Current versus Temperature

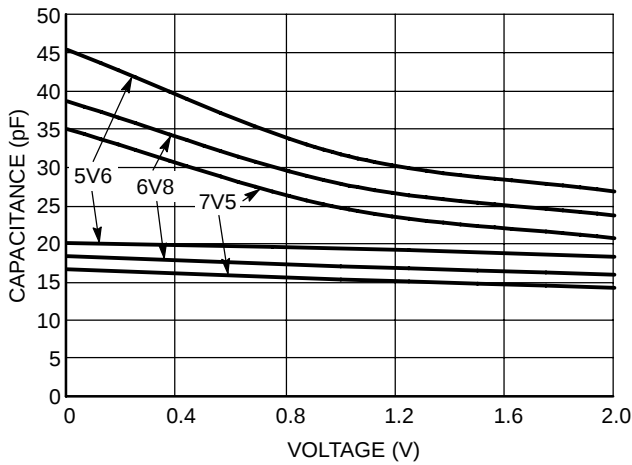


Figure 3. Typical Capacitance versus Bias Voltage
(Upper curve for each part is unidirectional mode, lower curve is bidirectional mode)

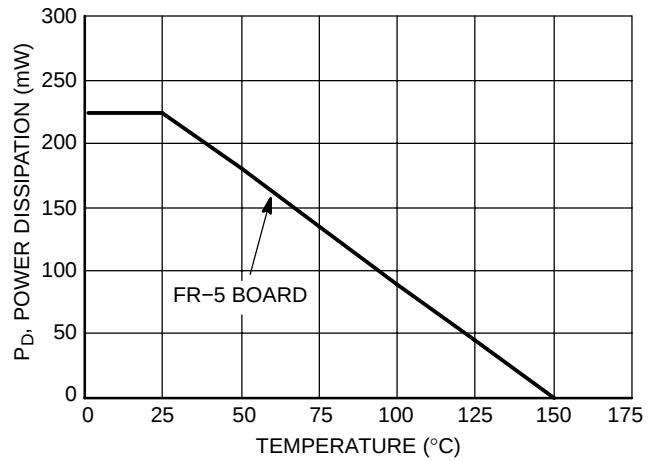


Figure 4. Steady State Power Derating Curve

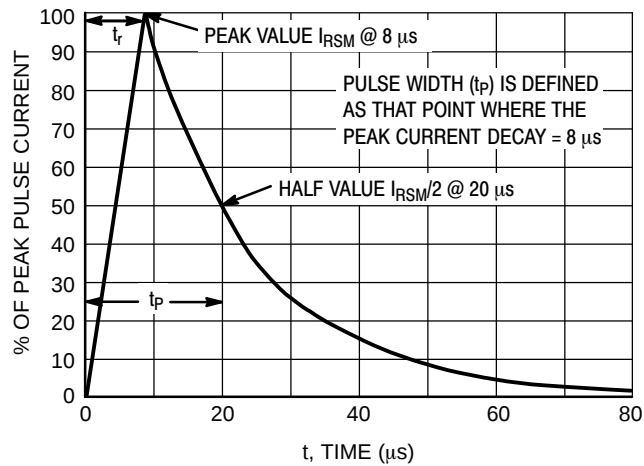


Figure 5. 8 X 20 μs Pulse Waveform

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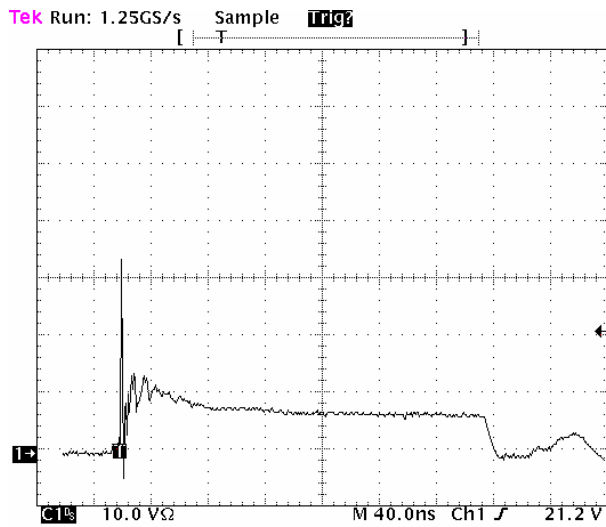


Figure 6. Positive 8 kV contact per IEC 6100-4-2
- NZL6V8AXV3T1G

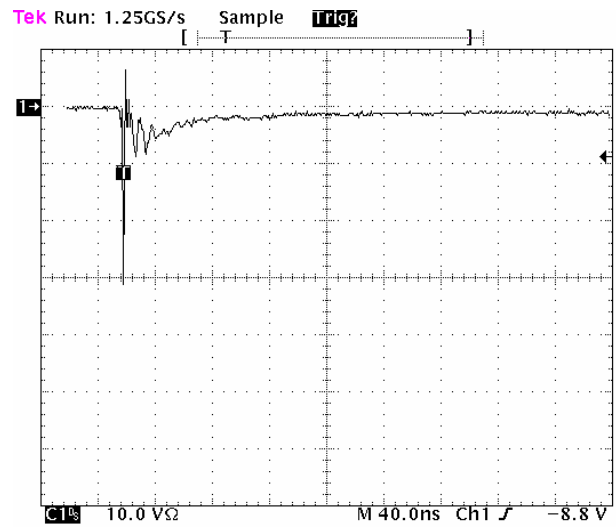


Figure 7. Negative 8 kV contact per IEC 6100-4-2
- NZL6V8AXV3T1G

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TYPICAL COMMON ANODE APPLICATIONS

A dual junction common anode design in an SC-89 package protects two separate lines using only one package. This adds flexibility and creativity to PCB design especially

when board space is at a premium. Two simplified examples of TVS applications are illustrated below.

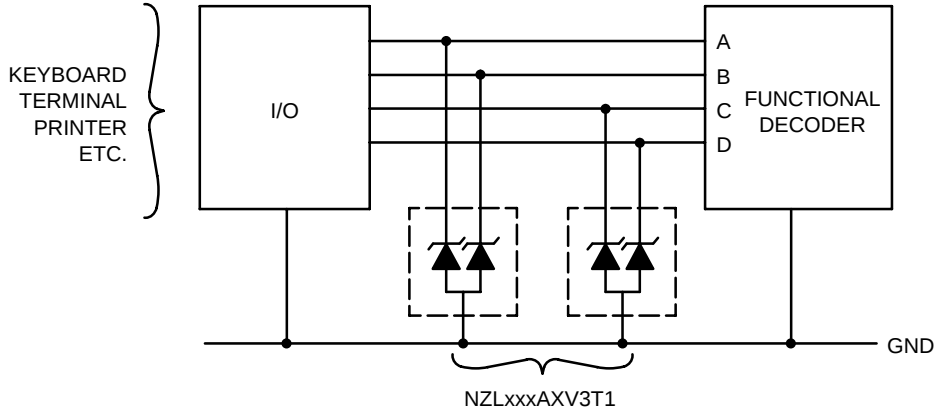


Figure 8. Computer Interface Protection

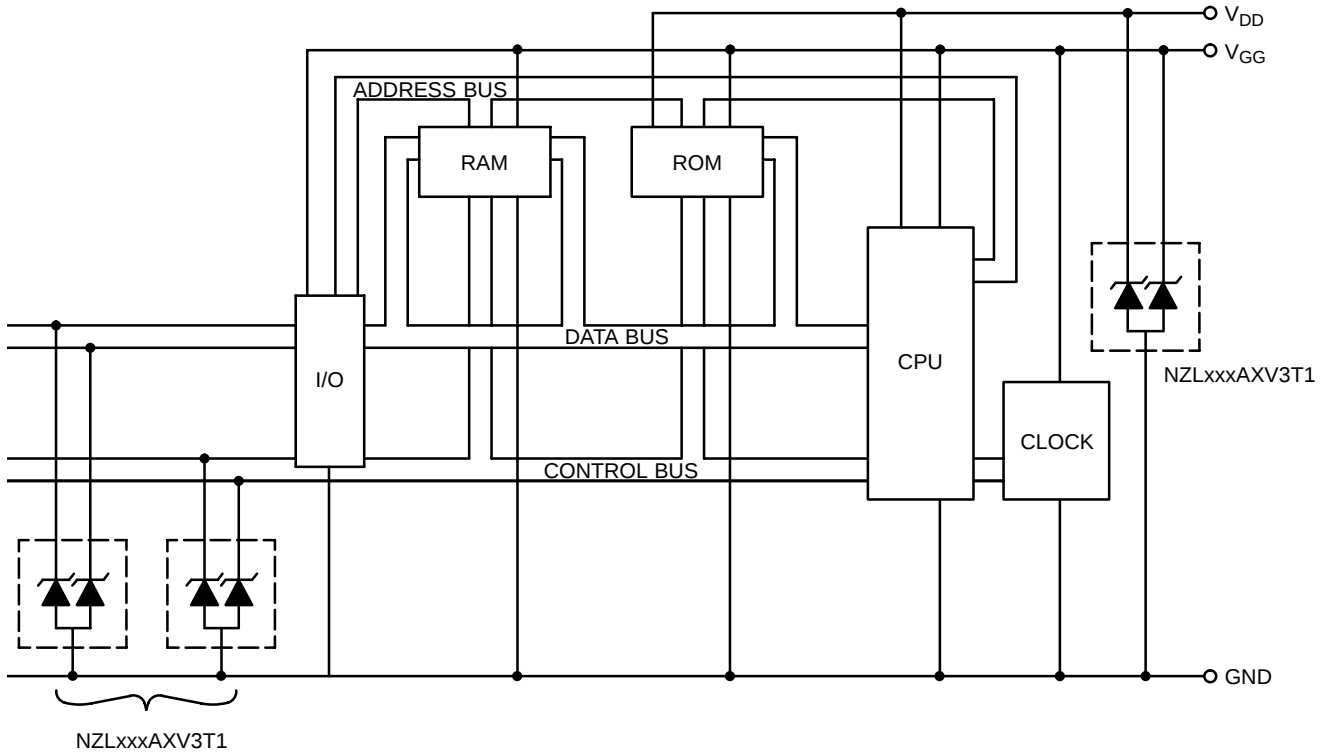
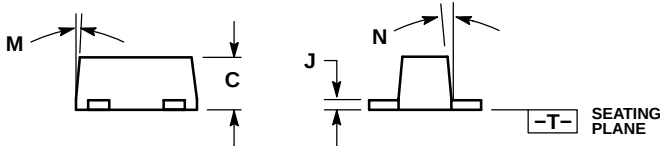
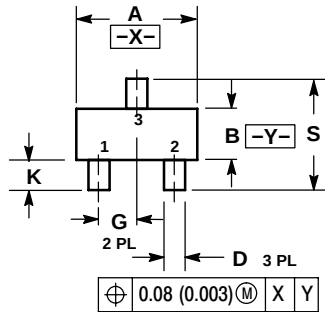


Figure 9. Microprocessor Protection

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PACKAGE DIMENSIONS

SC-89, 3-LEAD CASE 463C-03 ISSUE C



NOTES:

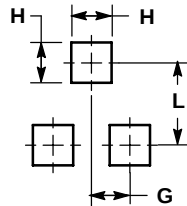
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 463C-01 OBSOLETE, NEW STANDARD 463C-02.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.60	1.70	0.059	0.063	0.067
B	0.75	0.85	0.95	0.030	0.034	0.040
C	0.60	0.70	0.80	0.024	0.028	0.031
D	0.23	0.28	0.33	0.009	0.011	0.013
G	0.50 BSC			0.020 BSC		
H	0.53 REF			0.021 REF		
J	0.10	0.15	0.20	0.004	0.006	0.008
K	0.30	0.40	0.50	0.012	0.016	0.020
L	1.10 REF			0.043 REF		
M	---	---	10	---	---	10
N	---	---	10	---	---	10
S	1.50	1.60	1.70	0.059	0.063	0.067

STYLE 4:

- PIN 1. CATHODE
- CATHODE
- ANODE

SOLDERING FOOTPRINT



RECOMMENDED PATTERN OF SOLDER PADS

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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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